

One-day Seminar on ANSYS CAE Solution: Paving the way for future semiconductor technology advancement.

Reported by KS Siow

Kuala Lumpur's MIMOS Berhad was alive with excitement on August 23rd as it hosted the highly anticipated MIMOS High Value Semiconductor Technology Seminar, focusing on the utilization of ANSYS software. With a diverse mix of 70 participants representing universities and companies, the event highlighted the versatile applications of the finite element software ANSYS. The full-day event was organized by MIMOS and co-organized by CAD-IT (Ansys representative in Malaysia), Ansys, and IEEE Electronics Packaging Society (Malaysia).



Throughout the seminar, attendees delved into ANSYS' diverse applications. Presentations and interactive discussions primarily explored the software's capabilities in semiconductor advanced packaging, advanced interconnect SI/PI modeling with additional discussions in the next-generation flexible electronics, enhancing reliability through electronics cooling, and advanced optoelectronics packaging solutions. The speakers included industry researchers as well as ANSYS certified application engineers. The seminar aimed to comprehensively portray how ANSYS Cad-IT is reshaping the landscape of semiconductor innovation.

The seminar served as a fertile ground for exchanging insights and igniting collaborations. Through interactive sessions and networking breaks, university researchers had the opportunity to exchange ideas with industry leaders and representatives from MIMOS. Such collaborations have the potential to give rise to innovative research initiatives, steering the semiconductor industry toward new horizon.

